ITS3: an innovative silicon ultra-thin and flexible tracker for the ALICE Experiment

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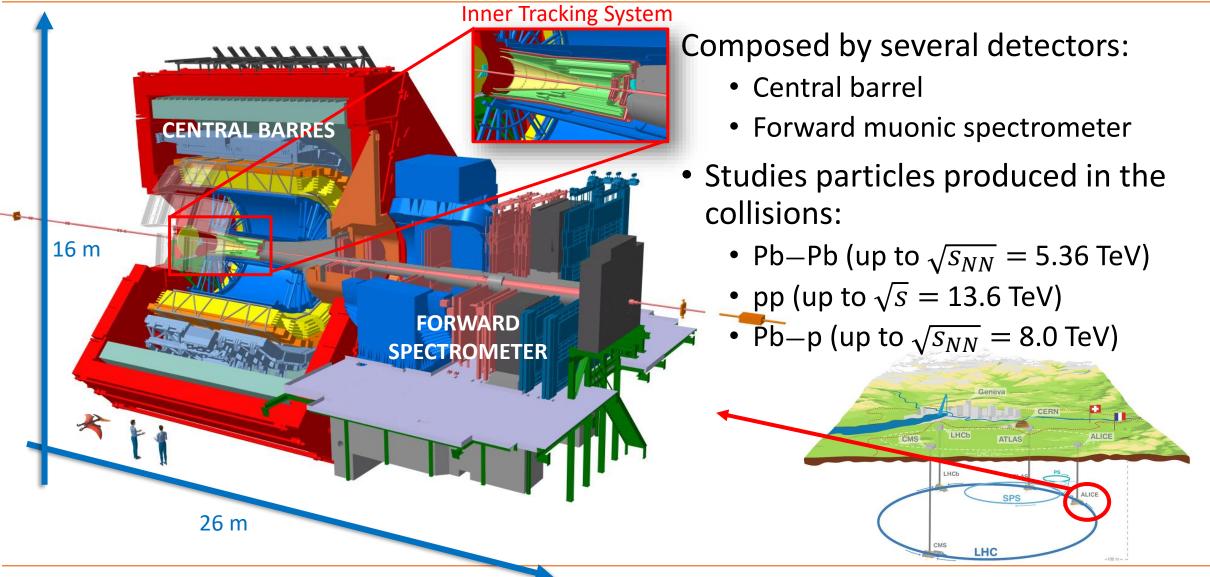
XXXIV International School "Francesco Romano"

on Nuclear, Subnuclear and Astroparticle Physics



The ALICE Experiment at LHC





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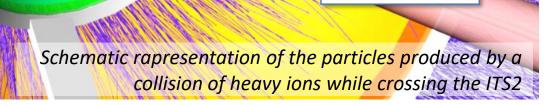


ITS functions:

- Reconstruction and discrmination of primary and secondary vertices π^*
- Charged particle tracking down to low value of momentum (~50 MeV/c)

ITS2 characteristics:

- 7 layers of Monolithc Active Pixel silicon Sensor (MAPS)
- 10 m² active area 147 cm
- **12.5** Gpixel
- Innermost radius of 22.4 mm



4 outer layers

40 cm

 B_0

3 inner layers

 D^0

Beampipe



The MAPS technology



ITS2, **24k** Monolithic Active Pixel silicon Sensors (MAPS), the ALPIDE:

- $3.0 \times 1.5 \text{ cm}^2 \text{ area}$
- matrix of 500k pixels

The ITS2 during the installation



The MAPS technology



ITS2: **24k** Monolithic Active Pixel silicon Sensors (MAPS)

Read-out logic: 11 μm Active layer: 15 μm Substrate: 24 μm

Schematic rapresentation of 4 MAPS pixels

- Read-out logic and active volume in the same silicon crystal
- Complete COMS circuitry inside the pixels
- Low material thickness (30-50 μm)

The ITS2 during the installation



Model of ITS3



The upgrade: towards the ITS3

Innermost layers of ITS2

2026

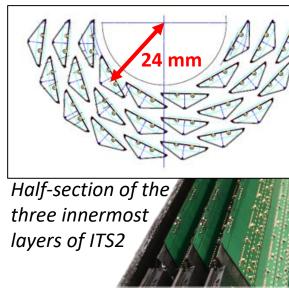


The upgrade: towards the ITS3



Model of ITS3

Innermost layers of ITS2



ITS3 characteristics:

Rimotion of the segmented structure by using flexible and large-area sensors

2026

• Reduction of the material budget introduced (0.3% \rightarrow 0.05% X₀/layer) and of the distance from the interaction point (24 \rightarrow 18 mm)

~28 cm

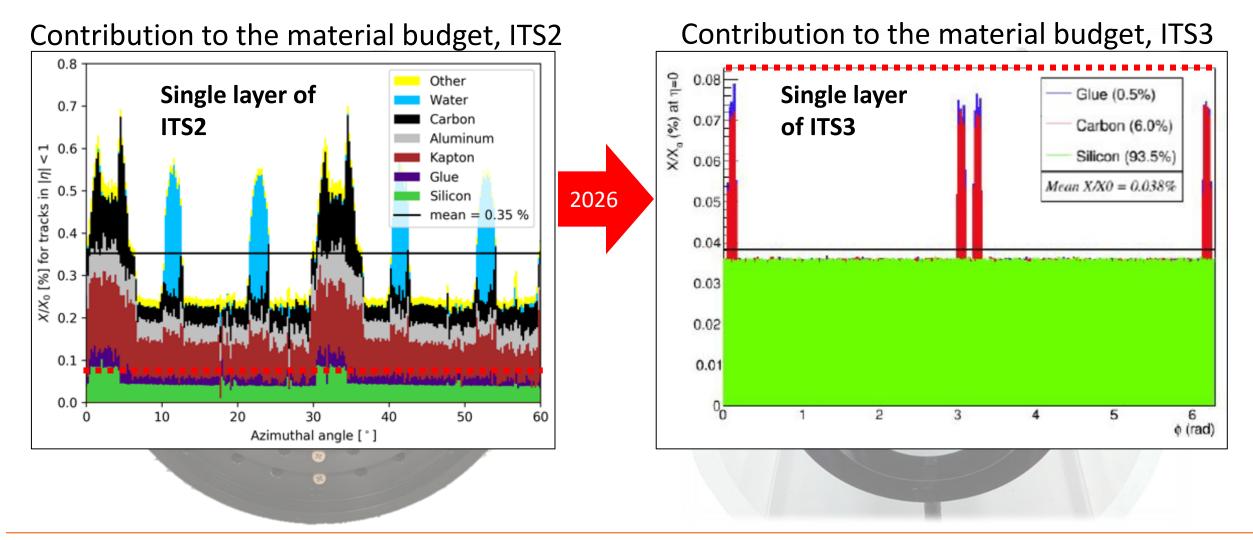
Half-section of the

three innermost

layers of the ITS3 model









ITS3: an innovative vertex detector



MAPS sensors for ITS3:

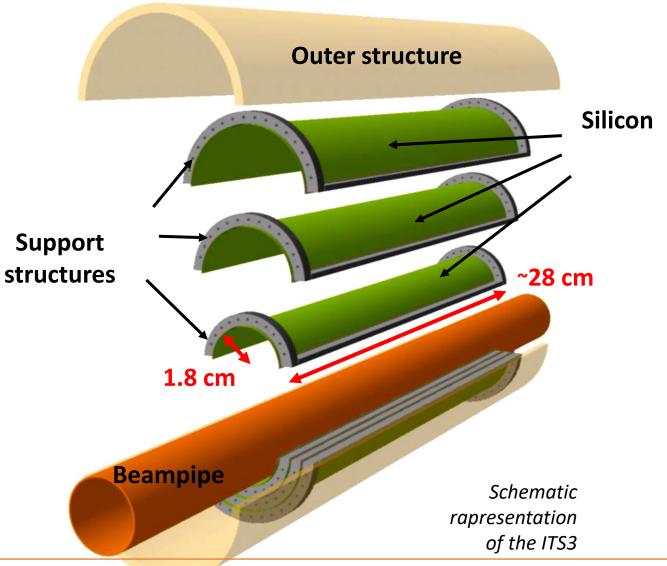
- Large-area (up to 28.0 × 9.4 cm²)
- Bent (minimum radius 18 mm, ITS2: 22.4 mm)
- Ultra-thin (20-40 μm, ITS2: 50 μm)

Performance improvement:

- Tracking efficiency
- Pointing resolution (factor 2×)

Important implications on the ALICE physics program, based on:

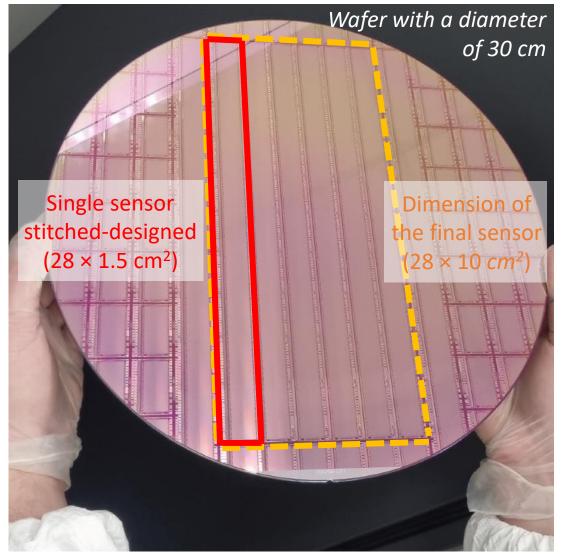
- Tracking down to low momentum
- Secondary vertex reconstruction





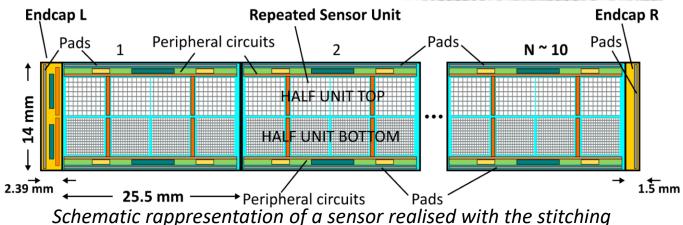
New technologies for the ITS3





- 65 nm CMOS TPSCo process: produced various test structures to validate its functionalities
- Stitching: repetition and chaining of the sensor functional unit: first stitched sensors produced and now under test







Characterisation of the test structures



Test structures realised to validate the 65 nm CMOS process

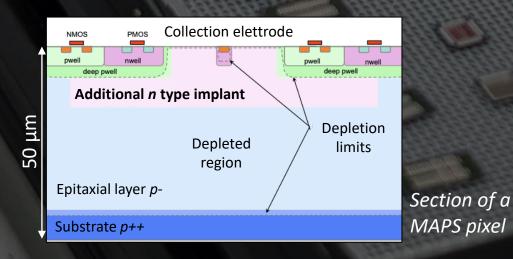


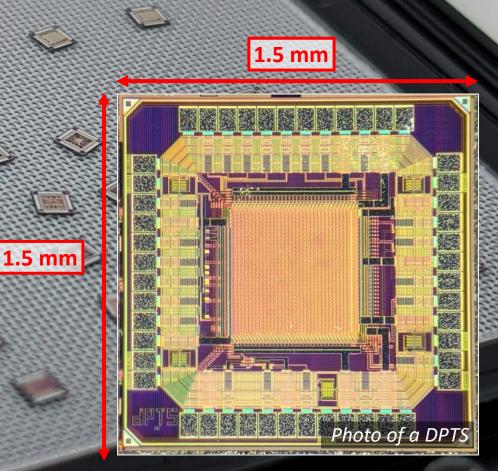
DPTS: Digital Pixel Test Structure



Characteristics:

- 0.5 × 0.5 mm² matrix
- 32 × 32 pixels
- Thickness of 50 μm
- Additional *n* type implant → complete depletion, charge collection faster, more uniform and more efficient





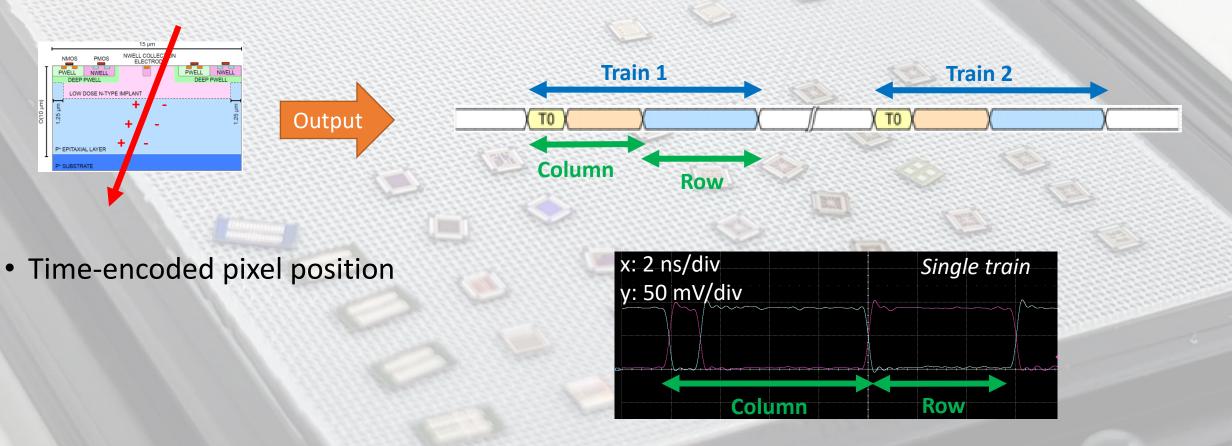
"Digital Pixel Test Structures implemented in a 65 nm CMOS process" [https://doi.org/10.1016/j.nima.2023.168589]



The output signal of the DPTS



Two output signals with opposite polarity:

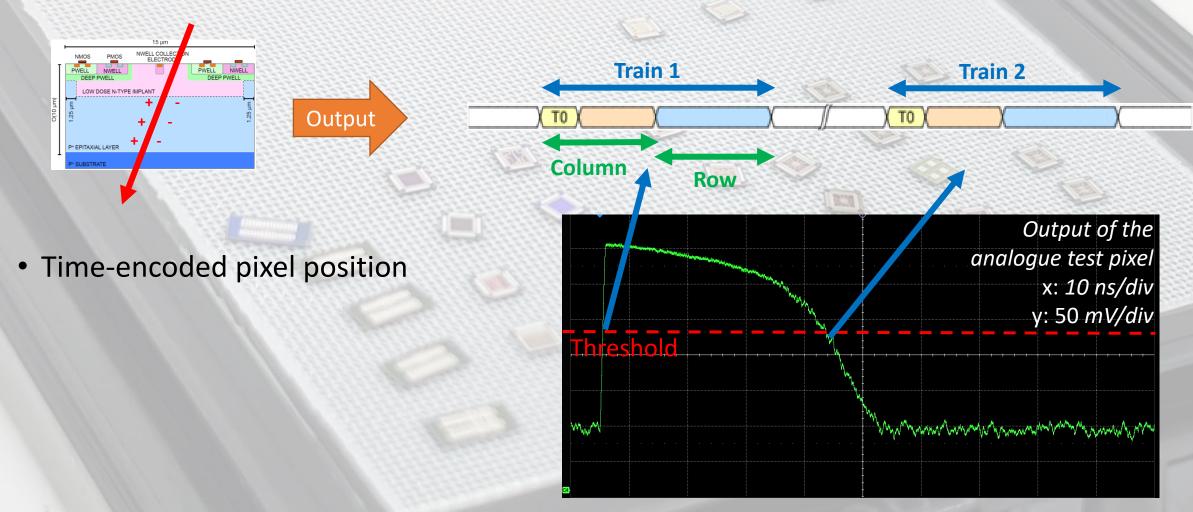




The output signal of the DPTS



Two output signals with opposite polarity:



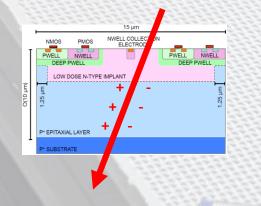


The output signal of the DPTS



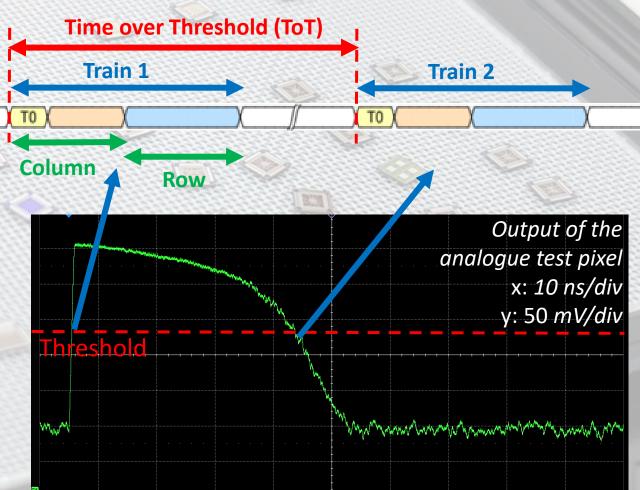
Two output signals with opposite polarity:

Output



Time-encoded pixel position

 Measurement of the time over threshold of the analogue signal → quantity correlated to the amplitude of the analogue signal



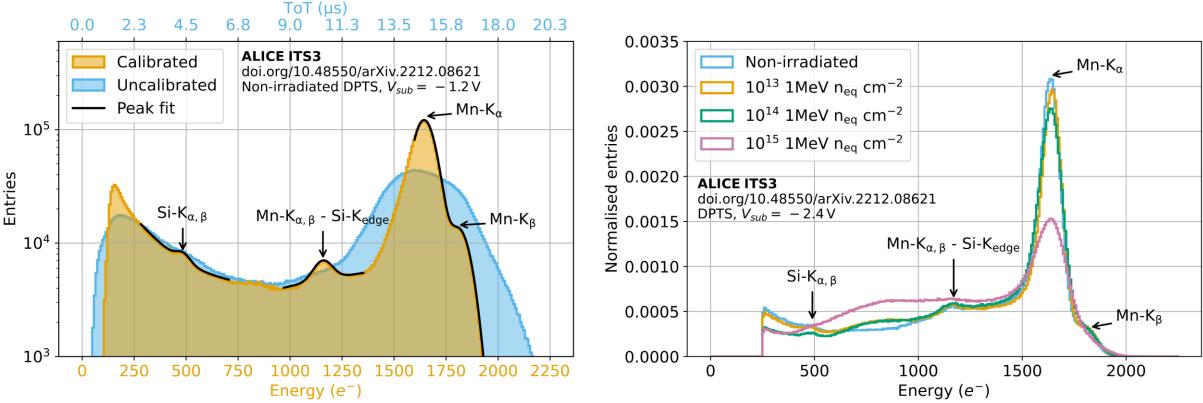


23/09/2023

ALICE

Response to a radioactive source: ⁵⁵Fe **Excellent energy response throught the ToT:**

• Resolution of the ⁵⁵Fe spectrum even after irradiation

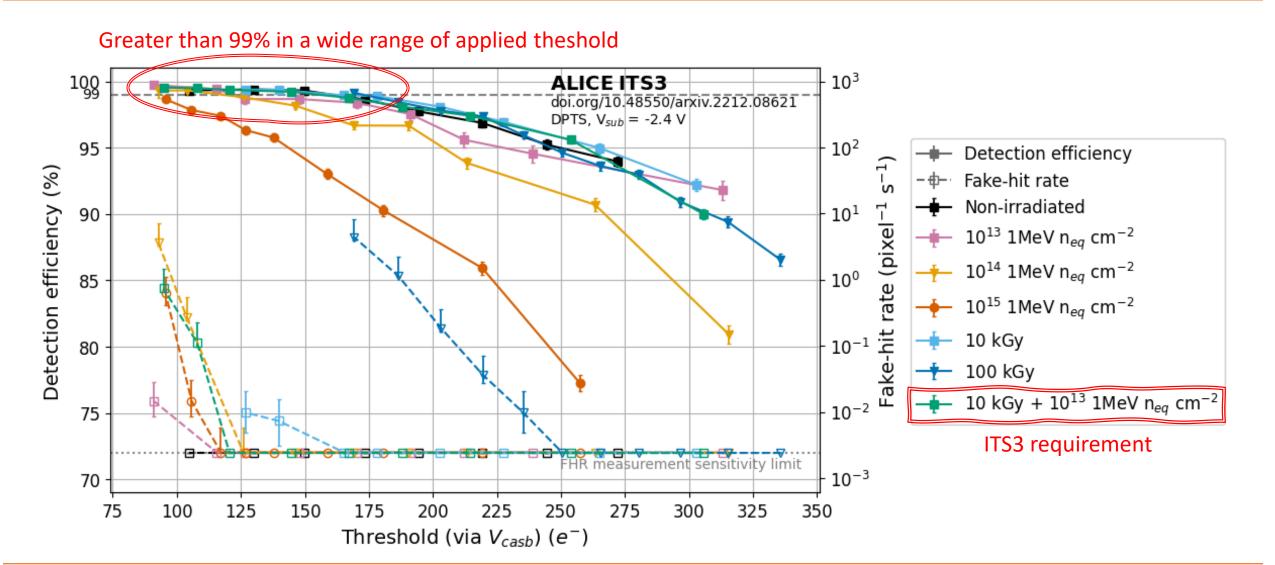


TERGES



Detection efficiency of MIP particles



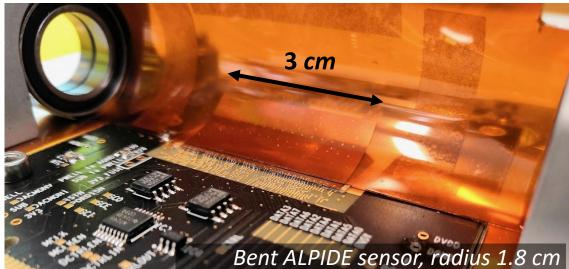


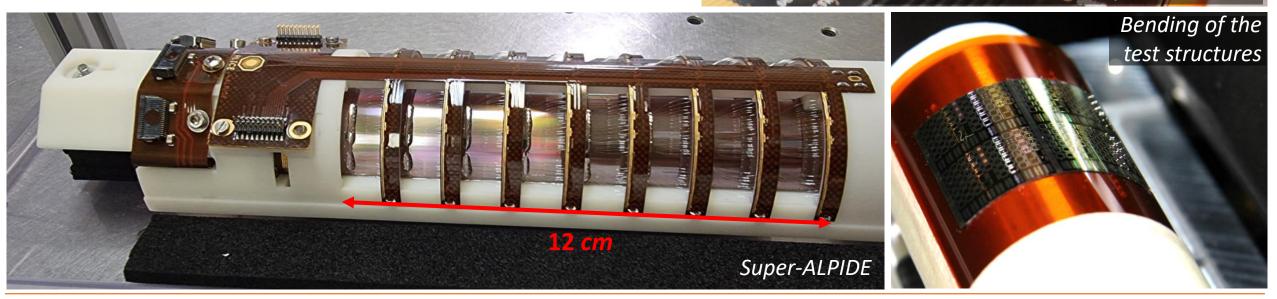


Bending of the MAPS sensors



- <u>2021</u>: "First demonstration of in-beam performance of bent Monolithic Active Pixel Sensors" [doi:10.1016/j.nima.2021.166280]
- <u>2022-2023</u>: Development of a prototype for mechanics and interconnections of a single bent layer
- <u>2023</u>: Bending and characterisation of the 65 nm CMOS bent test structures











- An **innovative vertex tracker** will be installed in 2026 for the ALICE Experiment. It will be made of large-area, flexible, bent **MAPS detectors**.
- The activities towards ITS3 are going on as scheduled:
 - The 65 nm CMOS process has been validated
 - The radiation hardness for both TID (up to 100 kGy) and NIEL (up to 10¹⁴ 1 MeV n_{eq} cm⁻²) was verified for the first test structures
 - An excellent response to X-rays in terms of energetic resolution was obtained
 - Promising results have been obtained from the measurements with bent sensors
- The **ITS3** technology will be the **starting point** for the development of the new tracker for the future experiment **ALICE3**, proposed for run 5 and 6 of LHC









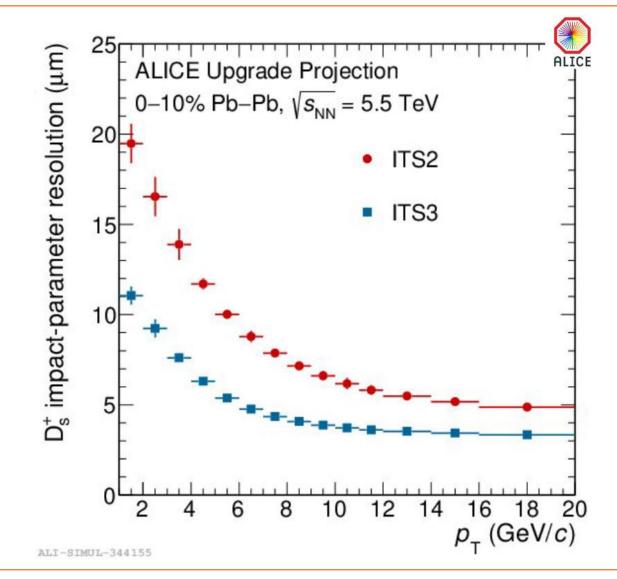


Backup



D meson

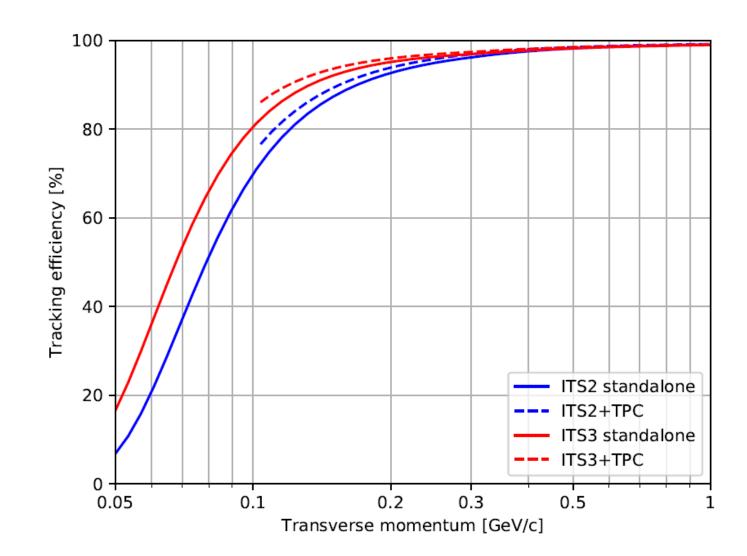






Tracking efficiency









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